

IN THE CLAIMS:

Please amend the claims as follows:

1. (Currently Amended) A method of electrochemically and mechanically planarizing a surface of a substrate, comprising:
 - (a) providing ~~a basin containing~~ an electrically conductive solution and an electrode ~~disposed therein~~ in contact with the electrically conductive solution;
 - (b) disposing a polishing medium in contact with the electrically conductive solution;
 - (c) positioning a substrate having a conductive material formed thereon against the polishing medium so that a surface of the substrate contacts the electrically conductive solution and the polishing medium;
 - (d) applying a first positive potential between the polishing medium and the electrode for a first time period to remove conductive material from the substrate; and
 - (e) applying a second positive potential between the polishing medium and the electrode for a second time period to remove conductive material from the substrate, wherein the second potential is lower than the first potential.
2. (Currently Amended) The method of claim 1, wherein ~~the second potential is a zero potential~~ the polishing medium comprises an electrode.
3. (Currently Amended) The method of claim 1, wherein ~~the second potential is lower than~~ the first positive potential is between about 4 volts and about 8 volts, and the second positive potential is between about 0.5 volts and about 4 volts.
4. (Currently Amended) The method of claim 1, wherein the first positive potential is a pulsed potential with a waveform.

5. (Currently Amended) The method of claim 1, wherein the first positive potential is a pulsed potential with a waveform and the second positive potential is a pulsed potential with a waveform.
6. (Currently Amended) The method of claim 1, ~~wherein the first potential is a pulsed potential with a waveform and the second potential is a pulsed potential with a waveform and a negative polarity~~ further comprising providing relative motion between the substrate and the polishing medium.
7. (Currently Amended) The method of claim 1, ~~wherein the first potential is a pulsed potential with a waveform and the second potential is a zero potential~~ the polishing medium comprises a conductive portion, and the conductive portion comprises an electrode.
8. (Currently Amended) The method of claim 1, wherein the first positive potential is modulated within a predefined range of potentials.
9. (Currently Amended) The method of claim 1, wherein the second positive potential is modulated within a predefined range of potentials.
10. (Original) The method of claim 1, further comprising repeating steps (d) and (e) for a third time period.
11. (Currently Amended) The method of claim 1, wherein ~~applying the first potential comprises: applying a third potential between the polishing medium and the electrode for a third time period; and~~
~~applying a fourth potential between the polishing medium and the electrode for a fourth time period~~ the polishing medium comprises a conductive polishing material or a composite of a conductive polishing material disposed in a conventional polishing material.

12. (Currently Amended) The method of claim 11, wherein the ~~third potential is a pulsed potential with a waveform and the fourth potential is a pulsed potential with a waveform~~ conductive material comprises copper or tungsten.

13. (Currently Amended) The method of claim 1, ~~wherein applying the second potential comprises:~~

~~applying a third potential between the polishing medium and the electrode for a third time period; and~~

~~applying a fourth potential between the polishing medium and the electrode for a fourth time period~~ further comprising applying a third potential between the polishing medium and the electrode for a third time period, and the third potential is a zero potential.

14. (Currently Amended) The method of claim [13] 16, wherein the ~~third potential is a pulsed potential with a waveform and the fourth potential is a pulsed potential with a waveform~~ the third positive potential is between about 4 volts and about 8 volts.

15. (Original) The method of claim 1, wherein the first time period is greater than the second time period.

16. (Currently Amended) The method of claim 1, further comprising applying a third positive potential between the polishing medium and the electrode for a third time period.

17. (Currently Amended) The method of claim 16, wherein the third positive potential is a pulsed potential with a waveform.

18. (Currently Amended) The method of claim 16, wherein the first positive potential is a pulsed potential with a waveform, the second positive potential is a

pulsed potential with a waveform, and the third positive potential is a pulsed potential with a waveform.

19. (Currently Amended) The method of claim 1, further comprising
(f) applying a third positive or zero potential between the polishing medium and the electrode for a third time period; and
repeating steps (d) through (f) for a period of time.